

# D1FS6A

## Schottky Barrier Diodes

60V, 2.5A

### Feature

- Small SMD
- High Recovery Speed
- Low  $V_F$
- Based on AEC-Q101
- Pb free terminal
- RoHS:Yes

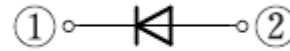
### OUTLINE

Package (House Name): 1F

Package (JEDEC Code): DO-214AC



### Equivalent circuit



### Absolute Maximum Ratings (unless otherwise specified : Tl=25°C)

Item	Symbol	Conditions	Ratings	Unit
Storage temperature	Tstg		-55 to 150	°C
Junction temperature	Tj		-55 to 150	°C
Repetitive peak reverse voltage	$V_{RRM}$		60	V
Average forward current	$I_F(AV)$	50Hz sine wave, Resistance load, Tl=103°C	2.5	A
Average forward current	$I_F(AV)$	50Hz sine wave, Resistance load, On alumina substrate, Ta=25°C ※	1.5	A
Average forward current	$I_F(AV)$	50Hz sine wave, Resistance load, On glass-epoxy substrate, Ta=25°C ※	1	A
Surge forward current	$I_{FSM}$	50Hz sine wave, Non-repetitive, 1 cycle, Peak value, Tj=25°C	60	A

※ : See the original Specifications

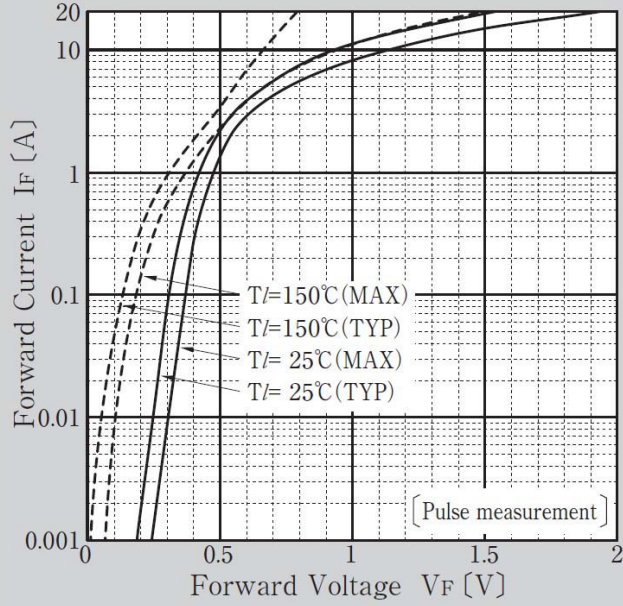
**Electrical Characteristics** (unless otherwise specified : Tl=25°C)

Item	Symbol	Conditions	Ratings			Unit
			MIN	TYP	MAX	
Forward voltage	$V_F$	$I_F=2.5A$ , Pulse measurement			0.57	V
Forward voltage	$V_F$	$I_F=1A$ , Pulse measurement			0.47	V
Reverse current	$I_R$	$V_R=60V$ , Pulse measurement			0.2	mA
Total capacitance	$C_t$	$f=1MHz$ , $V_R=10V$		80		pF
Thermal resistance	$R_{th(j-l)}$	Junction to lead			23	°C/W
Thermal resistance	$R_{th(j-a)}$	Junction to ambient, On alumina substrate ※			108	°C/W
Thermal resistance	$R_{th(j-a)}$	Junction to ambient, On glass-epoxy substrate ※			157	°C/W

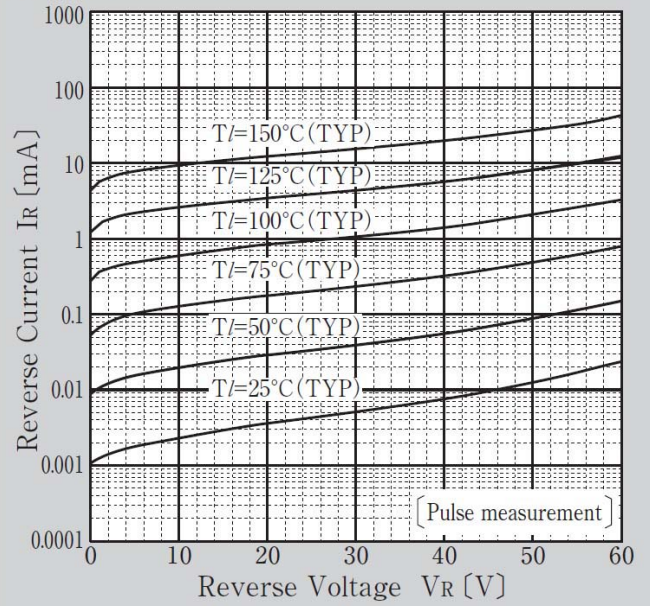
※ :See the original Specifications

# CHARACTERISTIC DIAGRAMS

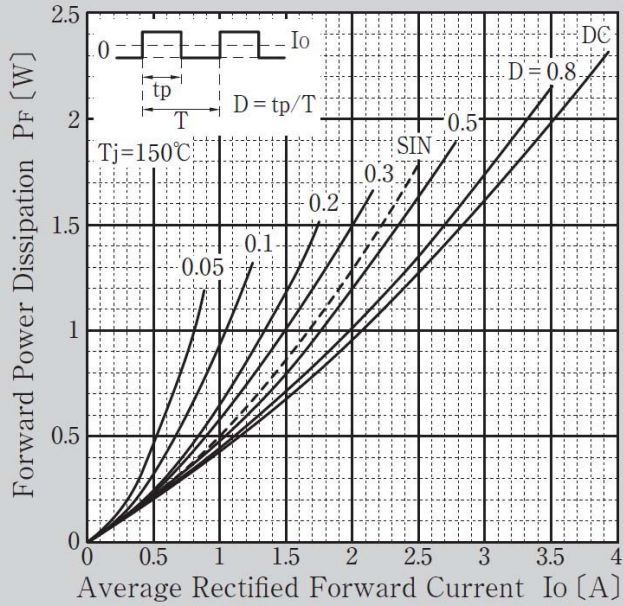
### Forward Voltage



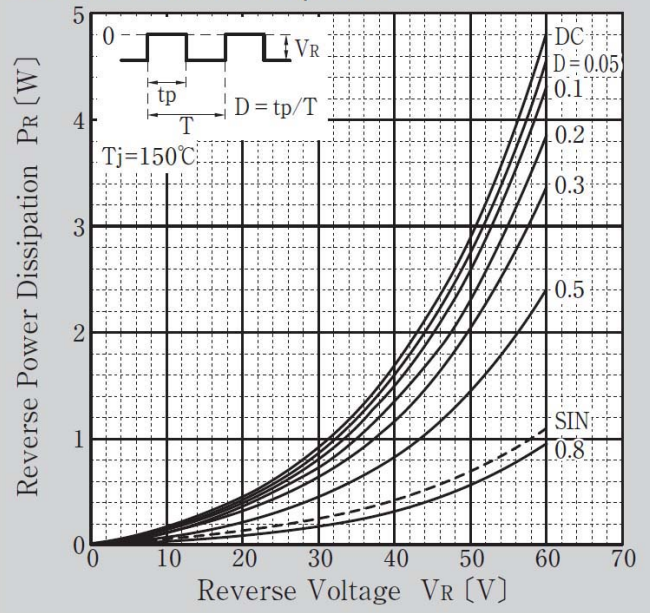
### Reverse Current

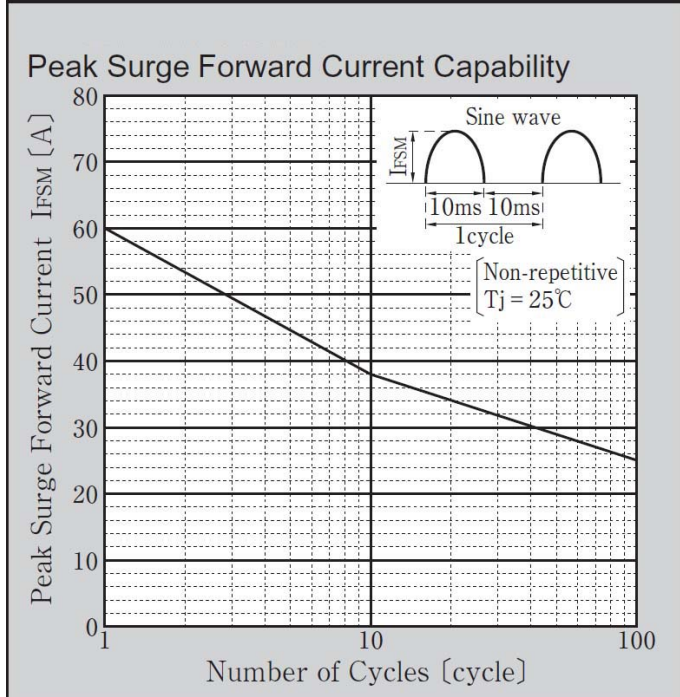
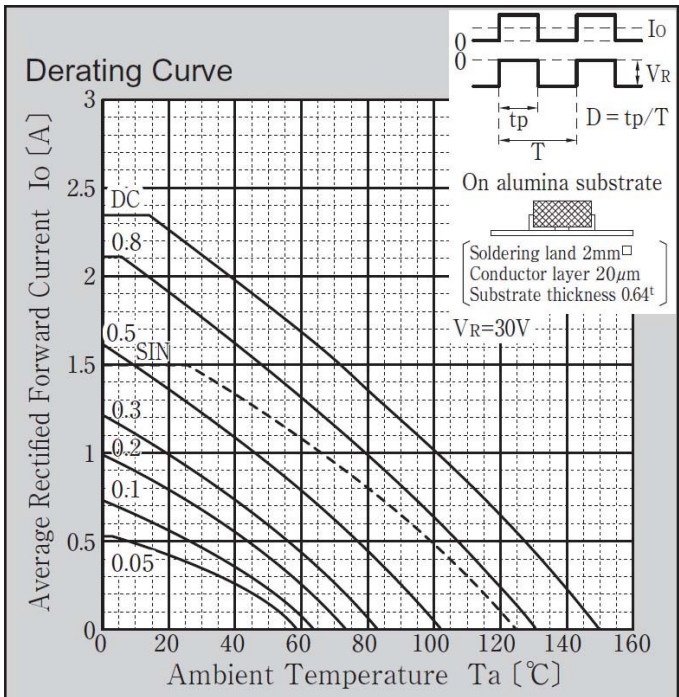
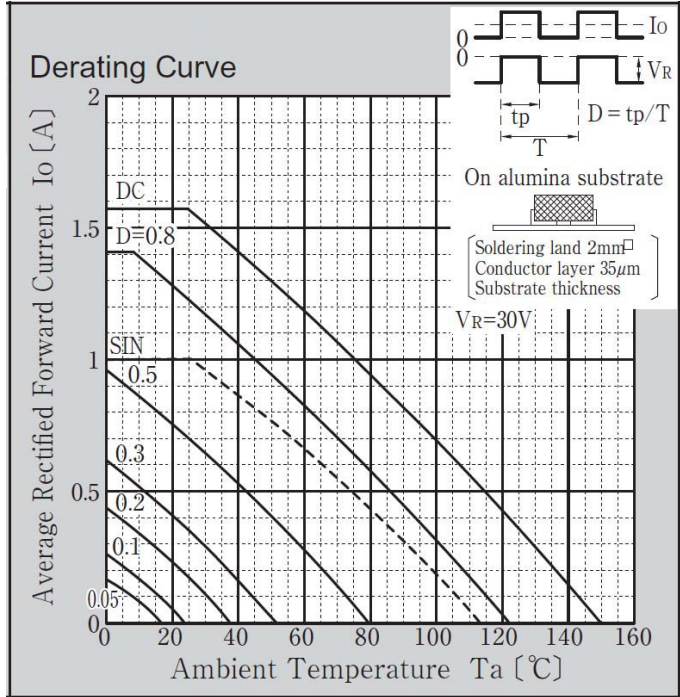
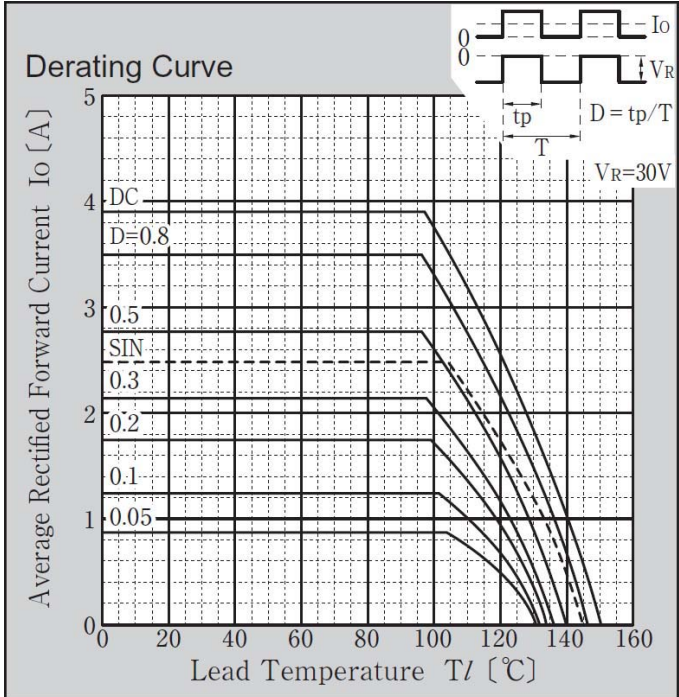


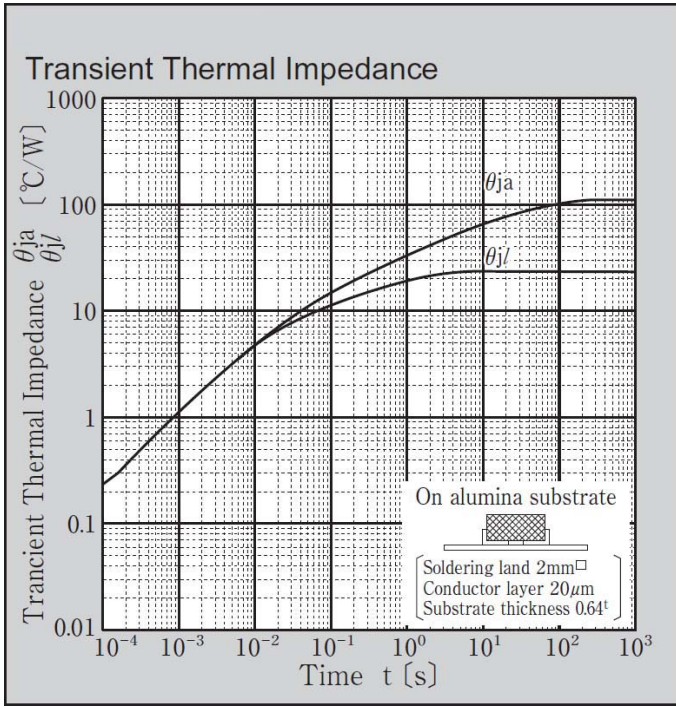
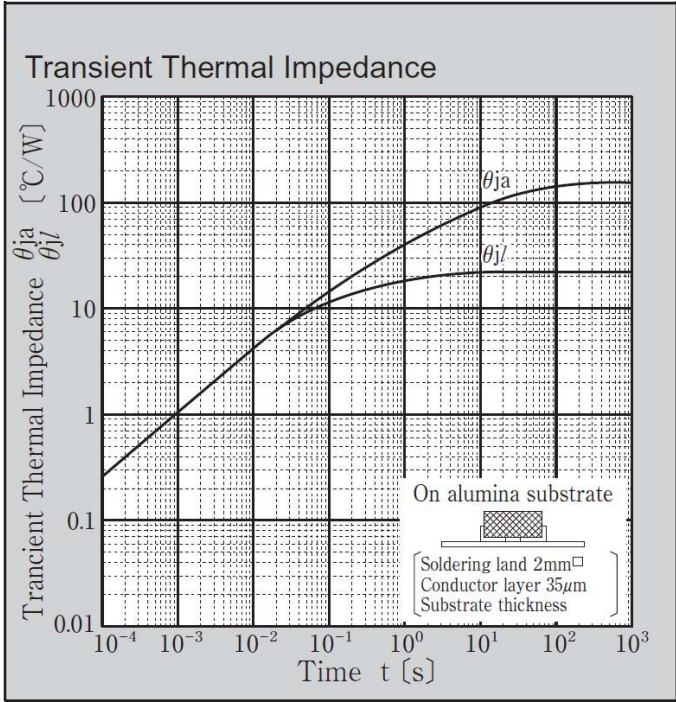
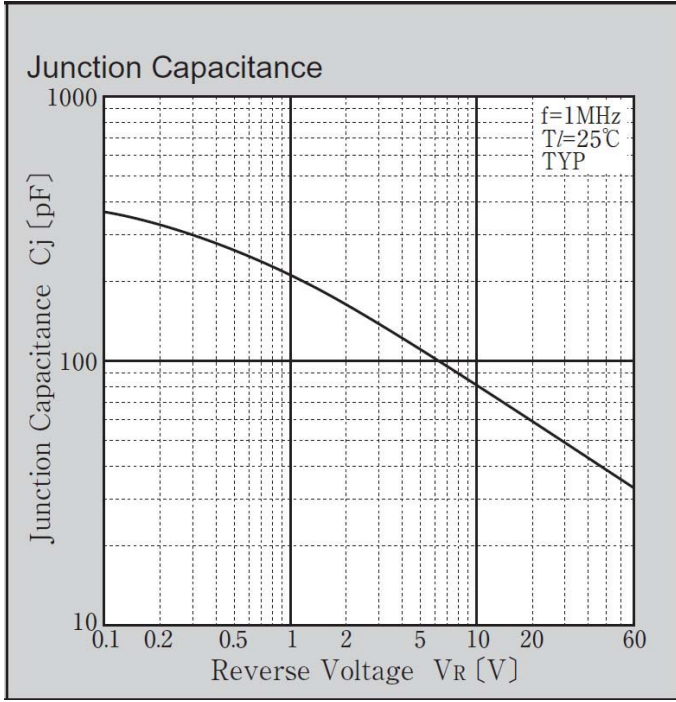
### Forward Power Dissipation



### Reverse Power Dissipation

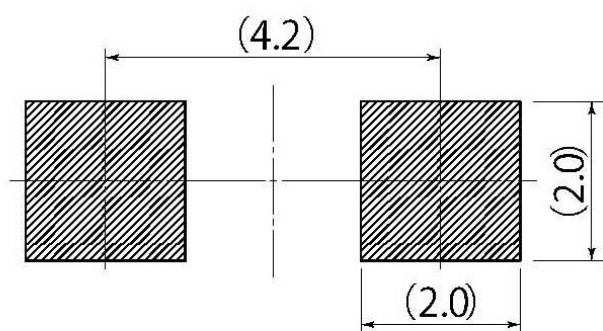
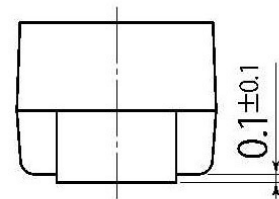
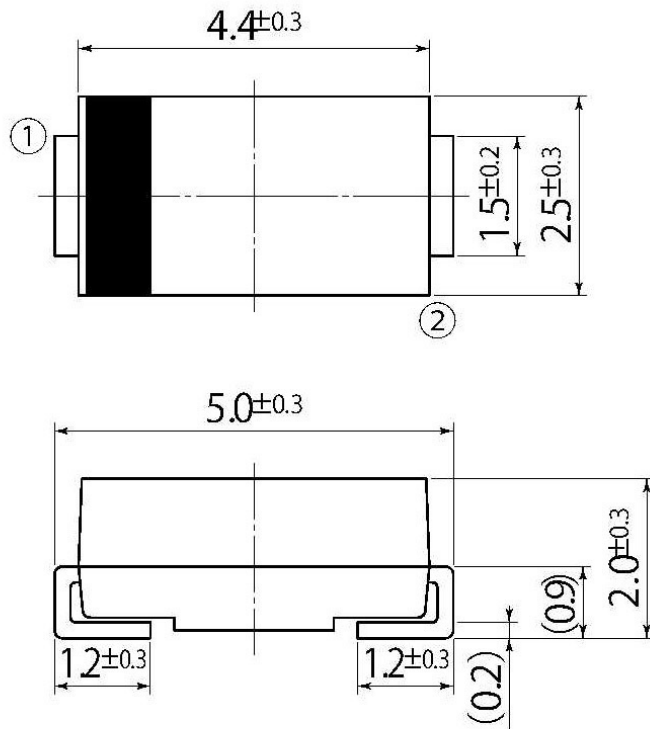






B3

JEDEC Code	DO-214AC
JEITA Code	-
House Name	1F



Referential Soldering Pad

• Optimize soldering pad to the board design and soldering condition.

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